

S6015

Halogen Free Resin Coated Copper Foil for HDI Multilayer Board

特点

- 不含卤素，无玻纤增强材料，适合HDI的高效率激光钻孔。
- 可与常规FR-4粘结片媲美的存放期。
- 优良的铜箔结合力和优秀的耐碱洗性。
- 适应常规的HDI制作工艺。

应用领域

适应无卤化趋势的手持电子产品，如手机、PDA，摄录一体机等。

FEATURES

- Halogen-free, glass free dielectric, suitable for high efficient laser via formation for high density interconnect.
- Extended shelf life, comparable with conventional FR-4 prepreg.
- High copper peel strength and excellent alkaline resistance.
- Compatible with conventional HDI fabrication process.

APPLICATIONS

Hand-held electronics such as mobile phones, PDA and digital camcorders etc., to meet halogen free trend.

GENERAL PROPERTIES

| Test Item | Treatment Condition | Unit | Property Data | |
|-----------------------|---------------------------|-------|--------------------|-----------------|
| | | | SPEC | Typical Value |
| Tg | DSC | | 140 | 145 |
| Flammability | C-24/23/50 | - | UL94V-0 | UL94V-0 |
| | E-24/125+des | | | |
| Volume Resistivity | After moisture resistance | M -cm | 10 ⁶ | 10 ⁸ |
| | E-24/125 | | 10 ³ | 10 ⁷ |
| Surface Resistivity | After moisture resistance | M | 10 ⁴ | 10 ⁹ |
| | E-24/125 | | 10 ³ | 10 ⁶ |
| Dielectric Constant | C-40/23/50, 1MHz | - | 4.0 | 3.8 |
| | | | Dissipation Factor | 0.035 |
| Dielectric Strength | D-48/50+D-0.5/23 | KV/mm | 30 | 42 |
| Alkaline Resistance | 10%NAOH;90 /60min | % | - | No change |
| Thermal Stress | 288 ,20s | - | - | Pass |
| Pressure Cooking Test | 121 2atms,30min+288 ,20s | - | - | Pass |
| Peel Strength | 12 μ | N/mm | 0.80 | 1.2 |
| | Cu. Foil | | 0.70 | 1.1 |
| | 288 ,20s | | | |
| | 125 | | | |

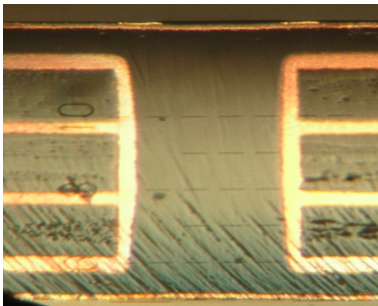
Explanations: C = Humidity conditioning;
D = Immersion conditioning in distilled water;
E = Temperature conditioning.

The figures following the letter symbols indicate with the first digit the duration of the preconditioning in hours, with the second digit the preconditioning temperature in and with the third digit the relative humidity.

S6015

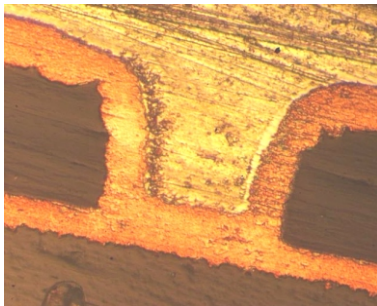
Halogen Free Resin Coated Copper Foil for HDI Multilayer Board

■ Excellent Hole Filling Capability



Hole plugging
directly by RCC resin

■ Laser via reliability



After 3 times 288 /10 Seconds
Soldering Thermal Shock

PURCHASING INFORMATION

| Copper Foil | Resin Thickness | Thickness Tolerance | Product Size |
|---------------------------------|-----------------|---------------------|----------------------|
| 12 μ m(T), 18 μ m(H) | 60-80 μ m | $\pm 5 \mu$ m | Available on request |

- ✘ The size and thickness could be available on request.
- ✘ Only B-stage,60T express that the resin thickness is 60 μ m,the copper style is 12 μ m.
- ✘ C-stage/B-stage,35/60T express that C-stage resin thickness is 35 μ m, B-stage resin thickness is 60 μ m,the copper style is 12 μ m.

HANDLING

- S6015 must be stored in vendor package, and avoid exposure to excessive moisture or temperature.
- Recommended storage conditions are 25 maximum at 50 \pm 5% relative humidity.